

ABSTRACT OF THE DISCLOSURE

A first substrate has a plurality of bumps and a second substrate has a plurality of openings at positions in registration 5 with the plurality of bumps when the first and second substrates are placed one on top of the other in a confronting manner. The first and second substrates are put together by fusing a sealing wall formed on the second substrate, to hermetically seal an electronic device lying on the first substrate therein. Gas that 10 may be generated upon fusing of the sealing wall can be effectively removed through the openings in the second substrate.

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